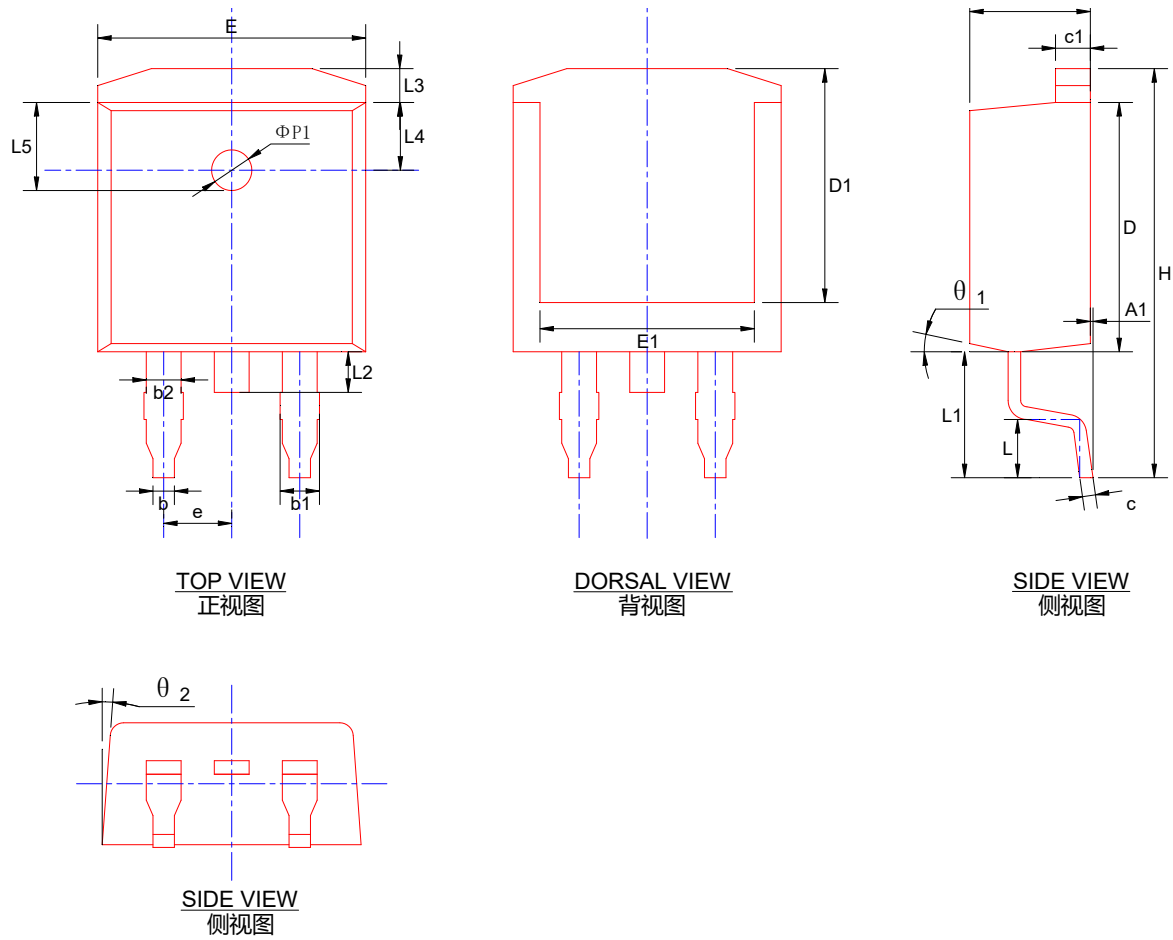


	深圳市锐骏半导体有限公司 ShenZhen Ruichips Semiconductor CO.,LTD	编号	RU-001-T0263-A-001
	封装外形尺寸（POD）规范	版本	A/1
		页次	17

T0263



NOTE:
1: ALL UNITS ARE IN MILLIMETER.
2: EJECTOR PIN MARK POSITION MAY VARY FROM DIFFERENT MOLD.
3: ALL DIMENSIONS REFER TO JEDEC.DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.300	4.500	4.700	0.169	0.179	0.185	E1	7.900	8.000	8.100	0.311	0.315	0.319
A1	0.000	0.100	0.250	0.000	0.005	0.010	L	1.850	2.150	2.450	0.073	0.085	0.096
b	0.700	*	1.000	0.028	*	0.039	L1	4.450	4.650	4.850	0.175	0.183	0.191
b1	1.140	*	1.470	0.045	*	0.058	L2	1.300	1.500	1.700	0.051	0.059	0.067
b2	1.170	1.270	1.370	0.046	0.050	0.054	L3	1.150	1.250	1.350	0.045	0.049	0.053
c	0.330	*	0.650	0.013	*	0.026	L4	2.400	2.500	2.600	0.094	0.098	0.102
c1	1.150	*	1.450	0.045		0.057	L5	2.900	3.000	3.100	0.114	0.118	0.122
D	8.590	*	9.400	0.338		0.370	e	2.540			0.100		
D1	7.650	7.750	7.850	0.301	0.305	0.309	Ø1	7°			7°		
H	14.700	15.100	15.790	0.579	*	0.622	Ø2	3°			3°		
E	9.800	10.000	10.200	0.386	*	0.402	ΦP	1.5REF			0.060		